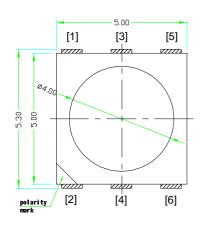


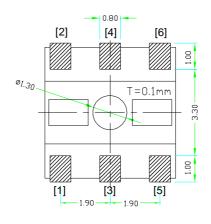
Feature

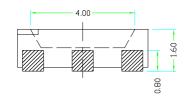
- ◆ Viewing angle:120 deg
- ◆ The materials of the LED dice is InGaN
- ◆ 5.30mm×5.00mm×1.60mm SMT-LED
- RoHS compliant lead-free soldering compatible

P/N: RF-INFA50DS-ED

Package Outline











NOTES:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are ±0.2mm (0.008inch) unless otherwise noted.



Absolute maximum ratings at Ta=25℃

Parameter	Symbol	Value	Unit
Power dissipation per chip	Pd	108	mW
Forward current per chip	lf	30	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-35 ~+85	$^{\circ}$
Storage temperature range	Tstg	-35 ~+85	${\mathbb C}$
Pulse Forward Current per chip	lfp	100	mA
Electrostatic Discharge	ESD	1000(HBM)	V

Electro-optical characteristics at Ta=25 $^{\circ}$ C

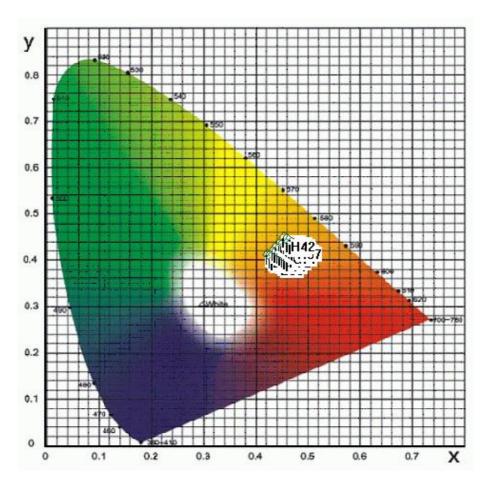
Parameter	Test Condition	Symbol	Value			Unit		
Parameter	Test Condition	Symbol	Min.	Тур.	Max.	Unit		
	lf=60mA	Vf	3.0		3.2	V		
Forward voltage			3.2		3.4	V		
			3.4		3.6	V		
Luminous intensity	lf=60mA	lv	4000	5000	7000	mcd		
Reverse current	rent Vr=5V				10	μΑ		
Color temperature If=60mA		Tc	2700		3100	K		
Chromotisit	If (0 A	E/F).3860) (0.4°).4298) (0.46				
Chromaticity	If=60mA	G/H	G/H (0.4726,0.4122) (0.4399,0.4385) (0.4563,0.4616) (0.4921,0.4327)					

NOTE: (Tolerance: Iv $\pm 10\%$, λ_d ± 2 nm, Vf ± 0.05 V, X, Y ± 0.01))

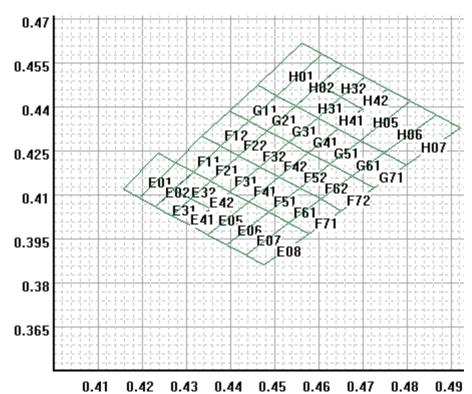
IFP Conditions: Pulse Width ≤ 10 msec. and Duty $\leq 1/10$.



CIE



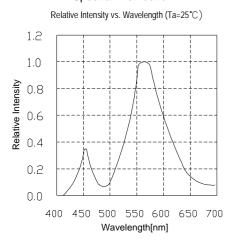
Chromaticity Bin

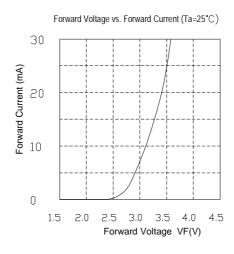


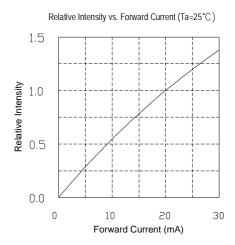


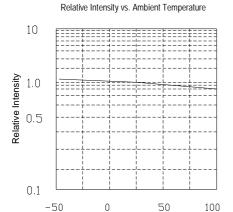
Typical optical characteristics curves

Spectral Distribution

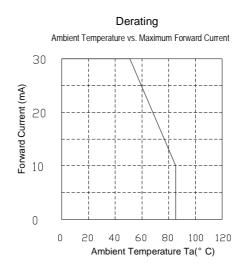








Ambient Temperature Ta(° C)



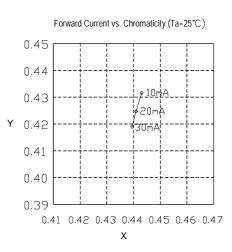
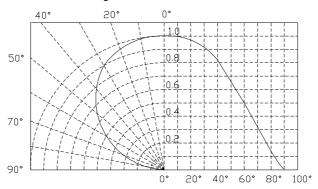


Diagram characteristics of radiation





Reflow profile

n Soldering condition

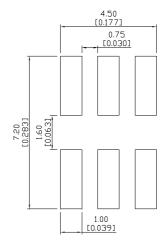
· Recommended soldering conditions

Reflow Soldering		Hand Soldering		
Pre-heat	160∼180℃	Temperature	300°C Max.	
Pre-heat time	120 seconds Max.			
Peak temperature	260°C Max.	Soldering time	3 second Max.	
Soldering time	10 seconds Max.		(one time only)	
Condition	Refer to Temperature-profile			

- After reflow soldering rapid cooling should be avoided
- **n** Temperature-profile (Surface of circuit board) Use the following conditions shown in the figure.

REFLOW PROFILE 10 SEC. MAX. MAX 260 FEMPERATURE C* 230 above 220°C 200 120 SEC. MAX 60sec max 170 140 110 80 50 20 180 240 TIME (SECONDS)

RECOMMEND PAD DESIGN (Units: mm)



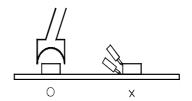
- 1. Reflow soldering should not be done more than two times
- 2. When soldering ,do not put stress on the LEDs during heating

n Soldering iron

- 1. When hand soldering, keep the temperature of the iron under 300°C, and at that temperature keep the time under 3 sec.
- 2. The hand soldering should be done only a time
- 3. The basic spec is \leq 5 sec. when the temperature of 260°C, do not contact the resin when hand soldering

n Rework

- 1. Customer must finish rework within 5 sec under 260°C
- 2. The head of iron can not touch the resin
- 3. Twin-head type is preferred.



n CAUTIONS

The encapsulated material of the LEDs is silicone . Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the picking up nozzle, the pressure on the silicone resin should be proper.



Reliability

(1) TEST ITEMS AND RESULTS

Туре	Test Item	Ref. Standard	Test Conditions	Note	Number of Damaged
	Resistance to Soldering Heat(Reflow Soldering)	JESD22-B106	Tsld=260°C,10sec	2 times	0/22
nental nce	Temperature Cycle	JESD22-A104	-40°C 30min ↑↓5min 100°C 30min	1000 cycle	0/100
Environmental Sequence	Thermal Shock	JESD22-A106	-40℃ 15min ↑↓ 100℃ 15min	1000 cycle	0/100
	High Temperature Storage	JESD22-A103	Ta=100°C	1000 hrs	0/100
	Low Temperature Storage	JESD22-A119	T _a =-40°C	1000 hrs	0/100
ation ence	Life Test	JESD22-A108	Ta=25°C I _F =30mA	1000 hrs	0/100
Operation Sequence	High Humidity Heat Life Test	JESD22-A101	60℃ RH=90% I _F =20mA	1000 hrs	0/100

(2) CRITERIA FOR JUDGING THE DAMAGE

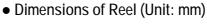
Item	Symbol	Test Conditions	Criteria for Judgement		
			Min.	Max.	
Forward Voltage	VF	IF=20mA	-	U.S.L*)×1.1	
Reverse Current	IR	VR=5V	-	U.S.L*)×2.0	
Luminous Intensity	IV	IF=20mA	L.S.L**)×0.7	_	

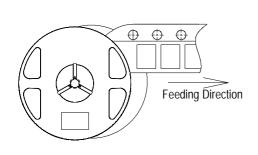
U.S.L.: Upper Standard Level L.S.L.: Lower Standard Level

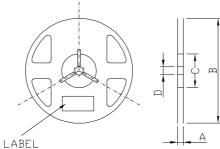


Packaging Specifications

Feeding Direction

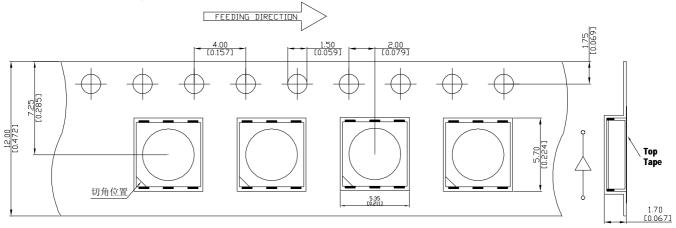






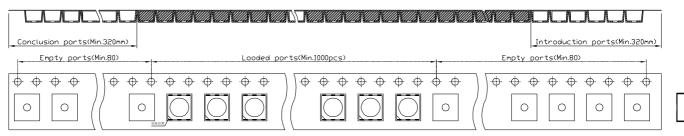
A	12±0.1mm
В	178±1mm
С	60±1mm
D	13.0 ± 0.5 mm

• Dimensions of Tape (Unit: mm)



Arrangement of Tape

Feeding Direction____

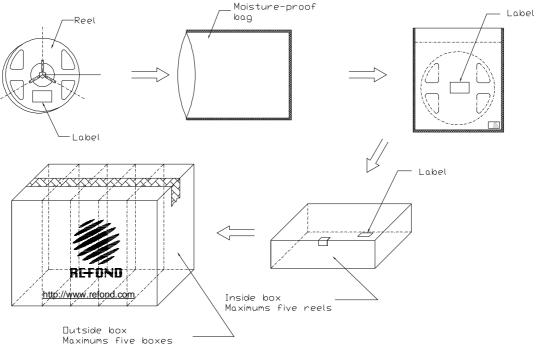


NOTES

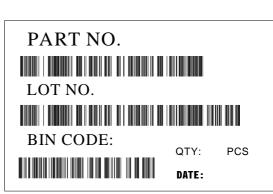
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
- 4. 1,000 pcs/ Reel.



Packaging specifications



■ Label



CAUTIONS

Package specifications

Reeled products (numbers of products are 1,000pcs) packed in a seal off moisture-proof bag along with a desiccant one by one, Four moisture-proof bag of maximums (total maximum number of products are 4,000pcs) packed in an inside box (size: about 250mm x about 250 x about 68mm) and Five inside boxes of maximums are put the outside box (size: about 360mm x about 265mm x about 255mm) Together with buffer material, and it is packed. (Pare No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. And quantity should appear on the label on the cardboard box.) The number of the loading steps of outside box (cardboard box) has three steps.

Storage conditions

Before opening the package:

The LEDs should be kept at 30°C or less and 70%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material (silica gel) is recommended.

After opening the package:

The LEDs should be kept at 30°C or less and 50%RH or less. If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.